	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
1	IS&R	3	("9107091").PN.	USPAT; JPO; DERWENT	2001/08/30 15:53		
2	BRS	118	chip with (circuit adj layer)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 16:15		
3	BRS	0	((chip with substrate) with (through adj hole)) and (ptfc or stess)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 16:30		
4	BRS	6045	chip and substrate and (through adj hole)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 16:30		
5	BRS	2	(chip and substrate and (through adj hole)) and (ptfc or stess)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 16:31		
6	BRS	871	(chip with substrate) with (through adj hole)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 16:33		
7	BRS	106	(chip with((insulat$ or dielectric)near substrate)) with (through adj hole)	USPAT; JPO; DERWENT; US-PGPUB; EPO;	2001/08/30 17:19	Truncation Overflow. Return string from Server is: '5'359193'	
8	BRS	381	(pcb or (dielectric adj substrate)) with (polytetrafluorothylene or ptfc or stress or relax$)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 17:47		
9	BRS	45	(pcb or (dielectric adj substrate)) and (polytetrafluorothylene or ptfc or stress or relax$) and ((via or through) near hole)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 17:29		
10	BRS	515	((pcb or (dielectric adj substrate)) and (polytetrafluorothylene or ptfc or stress or relax$) and ((through or via) adj hole)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:14		
11	BRS	49	((pcb or (dielectric adj substrate)) and (polytetrafluorothylene or ptfc or stress or relax$) and ((through or via) adj hole)) and ((stress or relax$) with layer)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:07		
12	BRS	91	257/409.ccls. and wafer	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:11		
13	BRS	86	wafer same (polytetrafluorothylene or ptfc or stress or relax$)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:15		
14	BRS	5486	wafer near (polytetrafluorothylene or ptfc or stress or relax$)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:58		
15	BRS	409	wafer near (polytetrafluorothylene or ptfc or stress or relax$)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:59		
16	BRS	5	wafer near (polytetrafluorothylene or ptfc)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:59		
17	BRS	5	wafer with (polytetrafluorothylene or ptfc)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:58		
18	BRS	5	wafer same (polytetrafluorothylene or ptfc)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:59		
19	BRS	5	chip with (polytetrafluorothylene or ptfc)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 18:59		
20	BRS	75	chip with (polytetrafluorothylene or ptfc)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 19:00		
21	BRS	65	wafer with (polytetrafluorothylene or ptfc)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 19:00		
22	BRS	5	wafer near (polytetrafluorothylene or ptfc)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 19:02		
23	BRS	10?	wafer with (polytetrafluorothylene or ptfc)	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 19:19		
24	BRS	379	wafer and (polytetrafluorothylene or ptfc) and chip	USPAT; JPO; DERWENT; US-PGPUB; EPO; IBM TDB	2001/08/30 19:19		

	Errors
1	0
2	0
3	0
4	0
5	0
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	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
25	BRS	361	(wafer and (polytetrafluoroethylene or ptfe) and chip) not (wafer with (polytetrafluoroethylene or ptfe))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/08/30 19:20		
26	BRS	109	(wafer and (polytetrafluoroethylene or ptfe) and chip) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/08/30 19:21		

Errors		
25	0	
26	0	